

1     ABSTRACT OF THE DISCLOSURE

2             The present invention includes integrated circuit devices,  
3 synchronous-link dynamic random access memory devices, methods of  
4 forming an integrated circuit device and methods of forming a  
5 synchronous-link dynamic random access memory edge-mounted device.  
6 According to one aspect of the present invention, an integrated circuit  
7 device includes a semiconductor die and a first housing encapsulating  
8 the semiconductor die. A heat sink is positioned proximate the first  
9 housing and a second housing is formed to encapsulate at least a  
10 portion of the heat sink. The heat sink is preferably thermally coupled  
11 with the semiconductor die and configured to expel heat therefrom.  
12 Another aspect provides a method of forming an integrated circuit  
13 device including the steps of providing a semiconductor die; forming a  
14 first housing about the semiconductor die; thermally coupling a heat sink  
15 with the first housing; and forming a second housing about at least a  
16 portion of the heat sink following the thermally coupling.

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